Kingbright

SURFACE MOUNT DISPLAY

KPDA04-105 HYPER RED

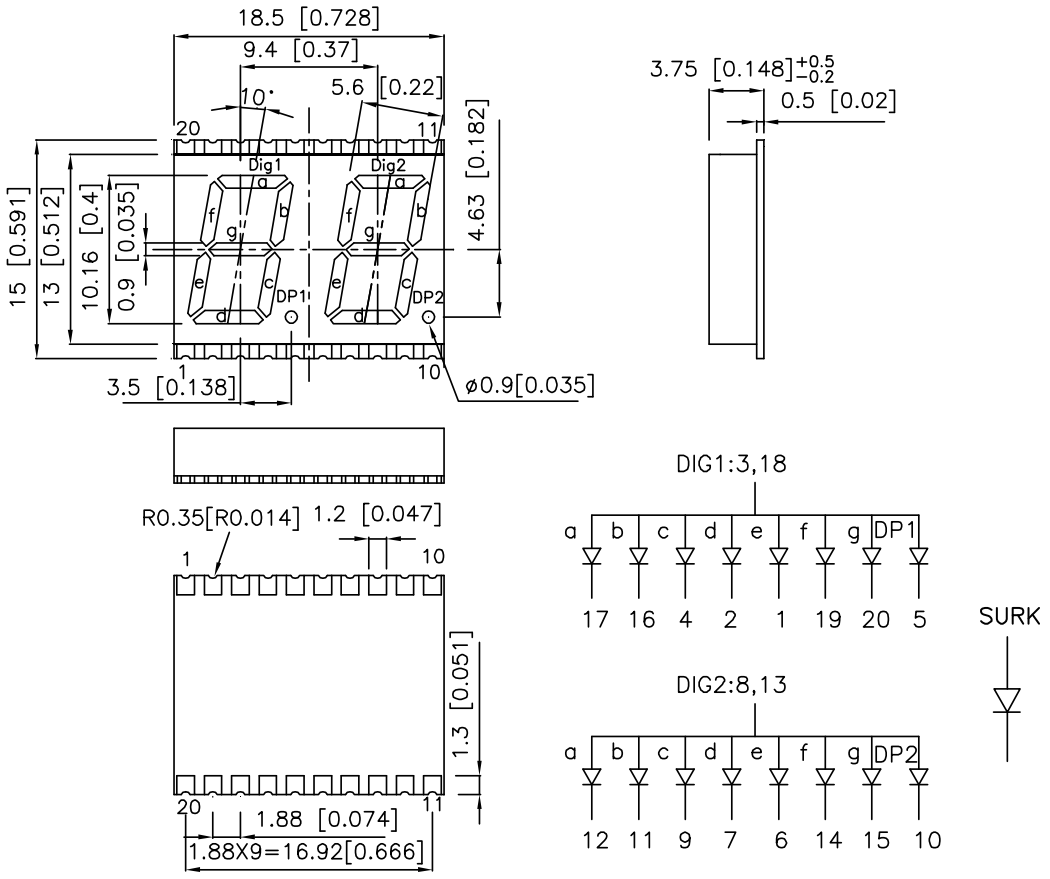
Features

- 0.4INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE,WHITE SEGMENT.
- PACKAGE:500PCS/ REEL.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions & Internal Circuit Diagram



Notes:
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
2. Specifications are subject to change without notice.

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Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) @ 10mA		Description
			Min.	Typ.	
KPDA04-105	HYPER RED (InGaAlP)	WHITE DIFFUSED	8000	26000	Common Anode, Rt. Hand Decimal.

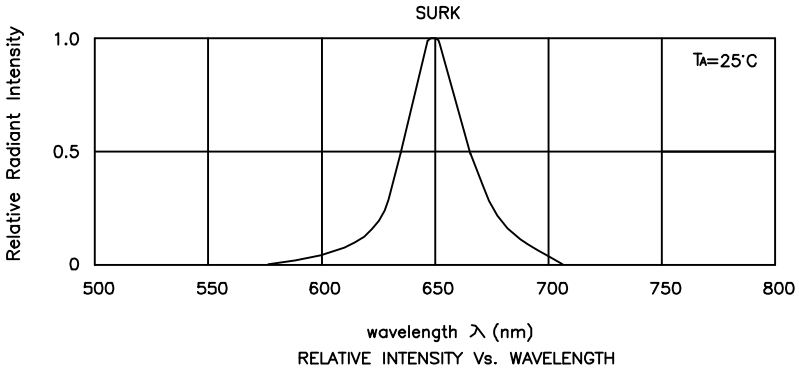
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	I_F=20mA
λD	Dominant Wavelength	Hyper Red	635		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	I_F=20mA
C	Capacitance	Hyper Red	35		pF	V_F=0V;f=1MHz
V_F	Forward Voltage	Hyper Red	1.95	2.5	V	I_F=20mA
I_R	Reverse Current	Hyper Red		10	uA	V_R = 5V

Absolute Maximum Ratings at T_A=25°C

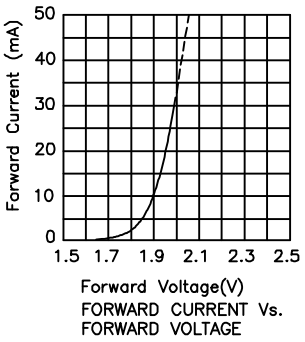
Parameter	Hyper Red	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

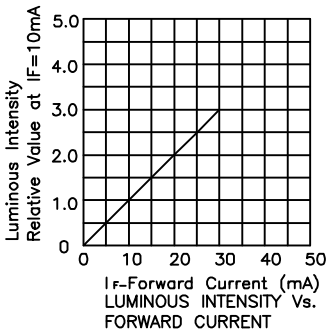


RELATIVE INTENSITY Vs. WAVELENGTH

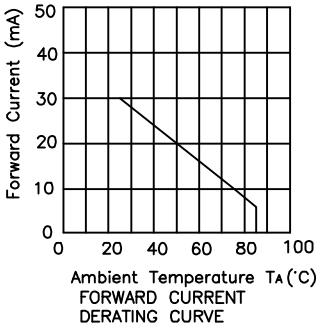
Hyper Red **KPDA04-105**



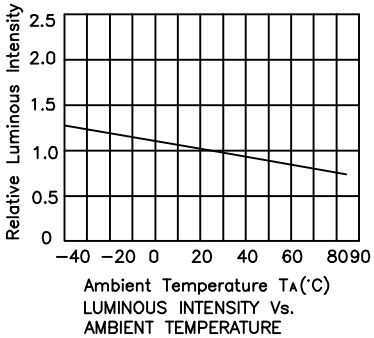
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE

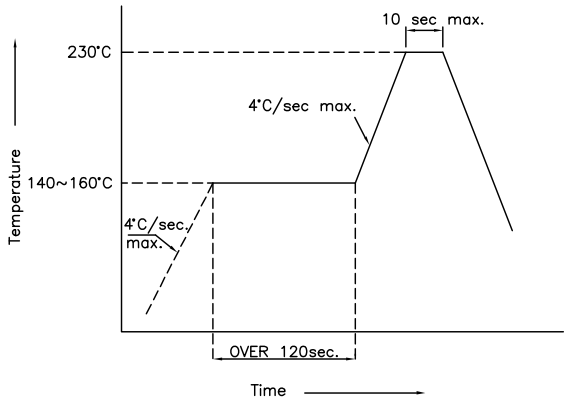


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

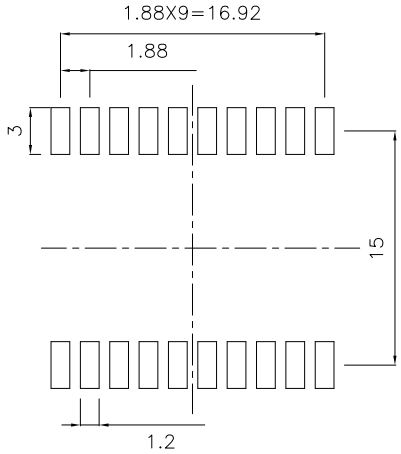
Remarks:
If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:
1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V
Note: Accuracy may depend on the sorting parameters.

KPDA04-105
SMT Reflow Soldering Instructions

Number of reflow process shall be 2 times or less and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern
(Units : mm)



Tape Specifications
(Units : mm)